

A Symposium on High-Performance Chips



Location TBD
Silicon Valley

Date TBD
late August 2018

Call for Contributions

AUTHORS' SCHEDULE

Submission date: **March 23, 2018**

Acceptance Notification: **May 1, 2018**

Final Version due: **July 16, 2018**

Poster Submissions due: **July 3, 2018**

AREAS OF INTEREST:

- **General-Purpose Processor Chips**
 - High Performance and Low Power
 - Multi-Core, Highly-Reliable Systems
- **Mobile and Embedded Devices**
 - Graphics/Multimedia/Game
 - SoC, Security, and DSP Chips
- **Communications and Networking**
 - Wireless LAN/WAN/PAN
 - Network and IO Processors
- **Emerging Computation Architectures**
 - Machine Learning, Vision and Graphics/ Compute Engines
 - Data Analytics and Big Data processing
 - IoT and Always-On Functions
 - Neuromorphic and Quantum Computing
- **Other Chips**
 - FPGAs and FPGA-Based Systems
 - Custom Chips for Emerging Applications
 - Open-Source Chips
- **Other Technologies**
 - Power and Thermal Management
 - Packaging and Testing
 - Display Technologies
 - On-Chip Optics & Sensors
 - Novel Computing Technologies
- **Memory Technologies**
 - Persistent Memory, Phase Change
 - Packaging, 3D, Stacked
- **Software for Multi-core, Heterogeneous Systems**
 - Programming models, Runtime systems
 - Performance, Power Debug and Evaluation

AUTHOR INFORMATION and FORMAT

Regular presentations are 30-minute talks. Submissions for consideration consist of an extended abstract with a maximum length of two pages. A select group of presenters will be invited to submit papers for inclusion in a special issue of IEEE Micro.

Poster submissions are also accepted from both industry and academia, and consist of 4 slides with a one-page summary. In particular, student posters describing applied research performed at a university are encouraged. The most outstanding student poster will receive the Best Student Poster Award.

Regular presentation and poster submissions are evaluated by the Program Committee on the basis of: performance of the device(s), degree of innovation, use of advanced technology, potential market significance and anticipated interest to the audience. Both regular presentation slides and posters are published in the Hot Chips proceedings. To submit, go to

<http://www.hotchips.org>

Send program-related questions and abstract to the program co-chairs Stefan Rusu and John Kubiataowicz at: program@hotchips.org, and send conference- and organization-related questions to the general chair, David Lau, at: info@hotchips.org. Check the Hot Chips 30 webpage for updates: <http://www.hotchips.org> and also for the Hot Chips 29 - 2017 proceedings under Archives which are now open to the public.

Sponsored by the Technical Committee on Microprocessors and Microcomputers
of the IEEE Computer Society, the IEEE Solid State Circuits Society
and In-Cooperation with the Association for Computing Machinery SIGARCH



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